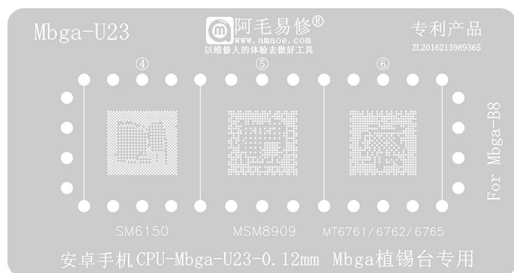


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## AMAOE BGA Mbga-U23 stencil reballing CPU SM6150 MSM8909 MT6761/6762/6765 for MBGA-B8

Product ID: 23005

Price: **7.00 EUR**

Product weight: **0.20 kg**

### Description:

AMAOE BGA Mbga-U23 stencil reballing CPU SM6150 MSM8909 MT6761/6762/6765 for MBGA-B8 - the sieves are a product made of steel resistant to high temperatures and deformations. Precise laser-cut templates facilitate positioning during work.

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